

Appl. No. 10/537,838
Amdt. Dated June 17, 2009
Reply to Office Action of March 19, 2009

Attorney Docket No. 88496.0008
Customer No.: 26021

REMARKS

This application has been carefully reviewed in light of the Office Action dated March 19, 2009. Claims 5 and 18 are canceled without prejudice. Claims 1, 3, 4, 6-14, 16, 17, 19, 20, and 22 are amended. Support for the amendment to the claims can be found in original claims 1, 5, and 21. New claims 26 and 27 are added. Claims 1, 3, 4, 6-14, 16, 17, 19, 20, 22, 26, and 27 remain in this application. Claims 1, 12-14, and 20 are the independent Claims. It is believed that no new matter is involved in the amendments or arguments presented herein.

Reconsideration and entrance of the amendment in the application are respectfully requested.

Art-Based Rejections

Claims 1, 3-14, 16-20, and 22 were rejected under 35 U.S.C. § 102(a), (b) or (e) as being anticipated by U.S. Patent No. US 6,824,827 (Katsuki). Applicant respectfully traverses the rejections and submits that the claims herein are patentable in light of the clarifying amendments above and the arguments below.

The Katsuki Reference

Katsuki is directed to surface treating a polyimide film having biphenyltetracarboxylic acid component (See *Katsuki, col. 3, lines 1-9 and Abstract*).

The Claims are Patentable Over the Cited References

The present application is generally directed to a laminate forming a copper metal layer on a polymeric film which has a smooth plane.

As defined by amended independent Claim 1, a method of preparing a laminate that includes a thermoplastic polyimide layer, and a metal layer on a surface of the thermoplastic polyimide layer includes a thermoplastic polyimide layer, and a metal

layer on a surface of the thermoplastic polyimide layer. The metal layer is formed by depositing a metal element while heating the thermoplastic polyimide layer.

Katsuki fails to disclose or suggest the above features of the claims of the present invention as defined by amended independent Claim 1. In particular, Katsuki fails to disclose or suggest, "wherein said metal layer is formed by depositing a metal element while heating the thermoplastic polyimide layer."

It is an aspect of the present invention that the metal layer is formed by depositing a metal element while heating the thermoplastic polyimide layer, adhesion between the metal layer and polyimide film is improved (*See Applicant's specification, at p. 6, line 26-p. 7, line 2; and p. 35, line 23-p. 36, line 18*).

The Office at p. 3, lines 12-14 of the Office Action states, "... Katsuki et al. specifically teach preheating the film to a temperature of 30 to 280°C prior to depositing the metal (Col. 7, lines 34-47; Examples 1-3)." However, in Katsuki, there is no teaching or suggestion that a polyimide layer is heated during a period when depositing a metal element.

In Katsuki, the film is heated in order to prevent moisture adsorbed on the film from oxidizing the metal layer and to improve denseness and uniformity of the metal layer (*See Katsuki col. 7, lines 34-38*). The function of the aforementioned heating of Katsuki is different from that of the present invention. In Katsuki, there is no teaching or suggestion that deposition with heating improves adhesion properties.

A comparison of Example 40 with Example 38 in the instant application reveals that Example 40 with heating of the thermoplastic polyimide layer improves the adhesion properties better than Example 38 without heating. Therefore, the adhesion properties of the present invention are excellent.

In summary, Katsuki does not disclose or suggest the above feature of the present invention as required by amended independent Claim 1.

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Since Katsuki fails to disclose, teach or suggest the above features recited in amended independent Claim 1, Katsuki cannot be said to anticipate nor render obvious the invention which is the subject matter of that claim.

Accordingly, amended independent Claim 1 is believed to be in condition for allowance and such allowance is respectfully requested.

Applicant respectfully submits that independent Claims 12-14 and 20 are allowable for at least the same reasons as discussed above with reference to amended independent Claim 1 and such allowance is respectfully requested.

The remaining claims depend either directly or indirectly from amended independent Claims 1, 12-14, and 20 and recite additional features of the invention which are neither disclosed nor fairly suggested by Katsuki and are therefore also believed to be in condition for allowance.

Conclusion

In view of the foregoing, it is respectfully submitted that the application is in condition for allowance. Reexamination and reconsideration of the application, as amended, are requested.

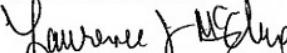
If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at the Los Angeles, California telephone number (310) 785-4600 to discuss the steps necessary for placing the application in condition for allowance.

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If there are any fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-1314.

Respectfully submitted,
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